

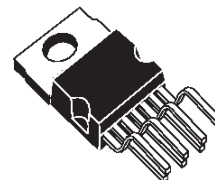
TV VERTICAL DEFLECTION OUTPUT CIRCUIT

The functions incorporated are :

- POWER AMPLIFIER
- FLYBACK GENERATOR
- REFERENCE VOLTAGE
- THERMAL PROTECTION

DESCRIPTION

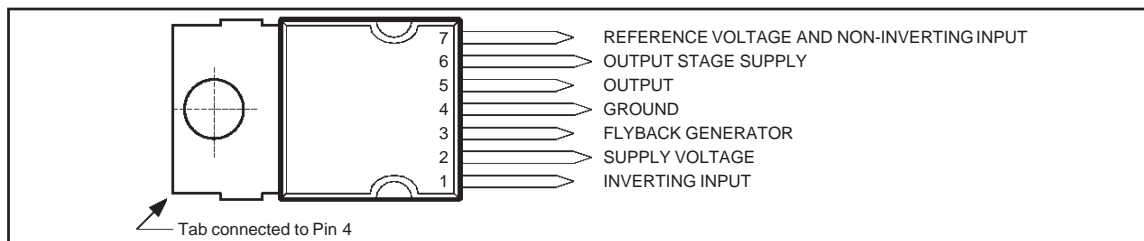
The TDA8170 is a monolithic integrated circuit in HEPTAWATT™ package. It is a high efficiency power booster for direct driving of vertical windings of TV yokes. It is intended for use in Colour and B & W television receivers as well as in monitors and displays.



HEPTAWATT
(Plastic Package)

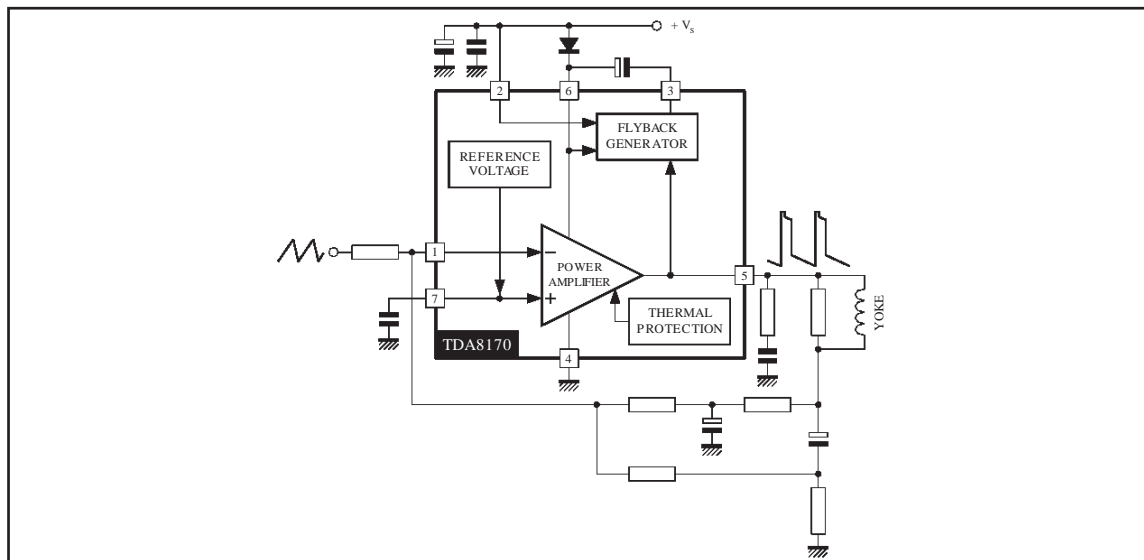
ORDER CODE : TDA8170

PIN CONNECTIONS



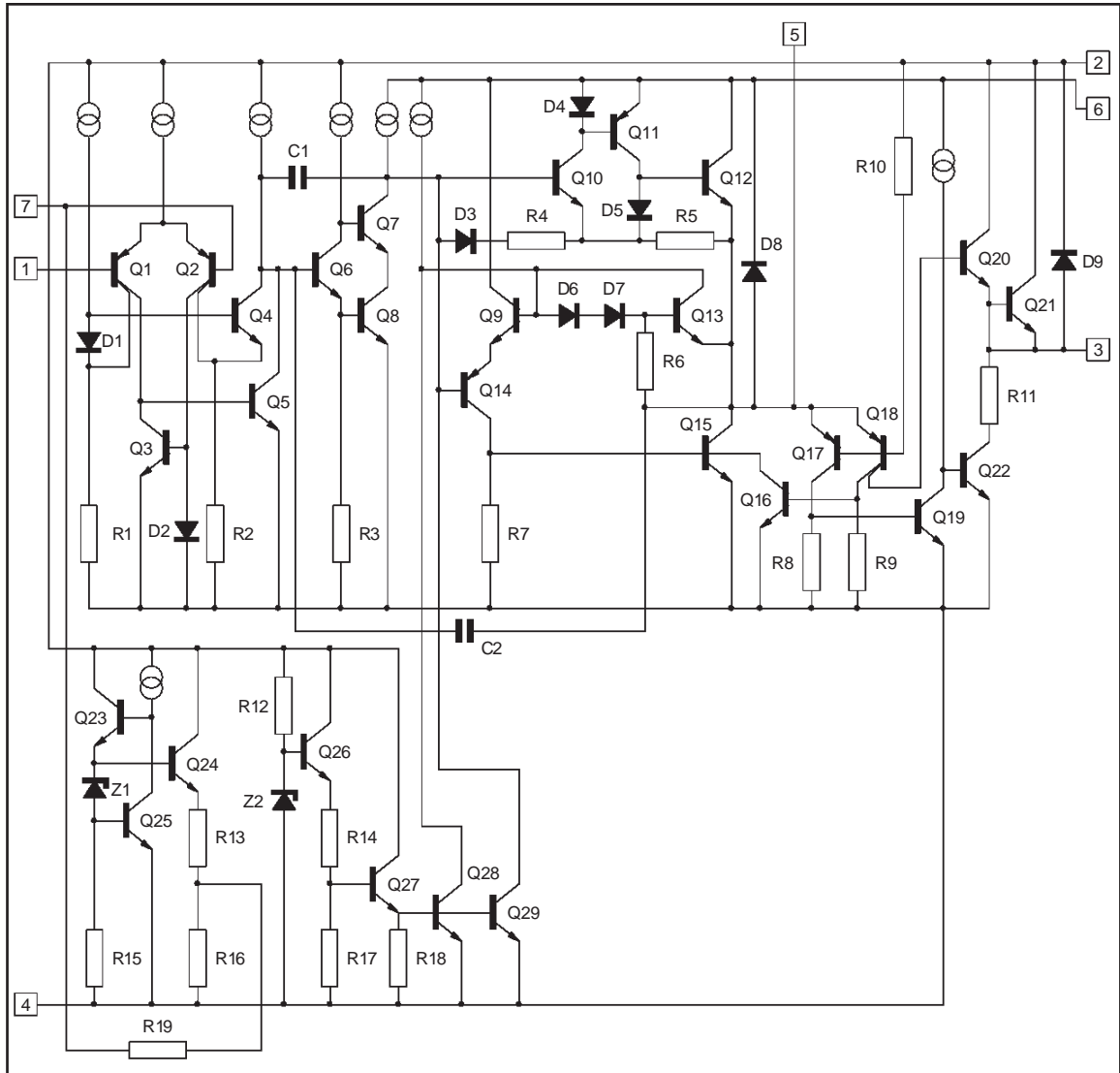
8170-01.EPS

BLOCK DIAGRAM



8170-02.EPS

SCHEMATIC DIAGRAM



ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V_S	Supply Voltage (pin 2)	35	V
V_5, V_6	Flyback Peak Voltage	60	V
V_3	Voltage at Pin 3	+ V_S	
V_1, V_7	Amplifier Input Voltage	+ $V_S, - 0.5$	V
I_o	Output Peak Current (non repetitive, $t = 2$ msec)	2.5	A
I_o	Output Peak Current at $f = 50$ or 60 Hz, $t \leq 10$ μ sec	3	A
I_o	Output Peak Current at $f = 50$ or 60 Hz, $t > 10$ μ sec	2	A
I_3	Pin 3 DC Current at $V_5 < V_2$	100	mA
I_3	Pin 3 Peak to Peak Flyback Current at $f = 50$ or 60 Hz, $t_{fly} \leq 1.5$ msec	3	A
P_{tot}	Total Power Dissipation at $T_{case} = 90$ °C	20	W
T_{stg}, T_j	Storage and Junction Temperature	- 40, +150	°C

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THERMAL DATA

Symbol	Parameter	Value	Unit
$R_{th j-case}$	Thermal Resistance Junction-case Max.	3	°C/W

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ELECTRICAL CHARACTERISTICS

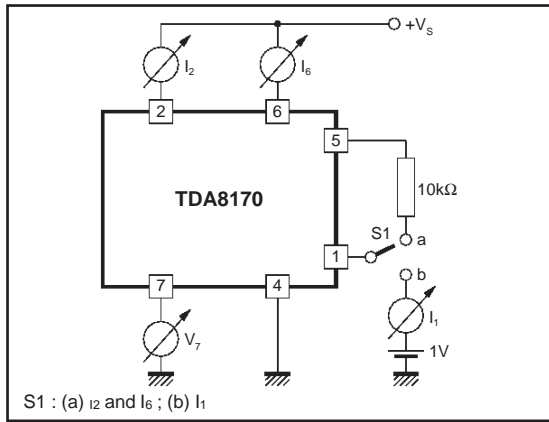
(refer to the test circuits, $V_S = 35$ V, $T_{amb} = 25$ °C unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit	Fig.
I_2	Pin 2 Quiescent Current	$I_3 = 0, I_5 = 0$		8	16	mA	1a
I_6	Pin 6 Quiescent Current	$I_3 = 0, I_5 = 0$		16	36	mA	1a
I_1	Amplifier Input Bias Current	$V_1 = 1$ V		- 0.1	- 1	μ A	1a
V_7	Reference Voltage			2.2		V	1a
$\frac{\Delta V_7}{\Delta V_S}$	Reference Voltage Drift versus Supply Voltage	$V_S = 15$ to 30 V		1	2	mV/V	1a
V_{3L}	Pin 3 Saturation Voltage to GND	$I_3 = 20$ mA		1		V	1c
V_5	Quiescent Output Voltage	$V_S = 35$ V, $R_a = 39$ k Ω		18		V	1d
		$V_S = 15$ V, $R_a = 13$ k Ω		7.5		V	1d
V_{5L}	Output Saturation Voltage to GND	$I_5 = 1.2$ A		1	1.4	V	1c
		$I_5 = 0.7$ A		0.7	1	V	1c
V_{5H}	Output Saturation Voltage to Supply	- $I_5 = 1.2$ A		1.6	2.2	V	1b
		- $I_5 = 0.7$ A		1.3	1.8	V	1b
T_j	Junction Temperature for Thermal Shut Down			140		°C	

8170-03.TEL

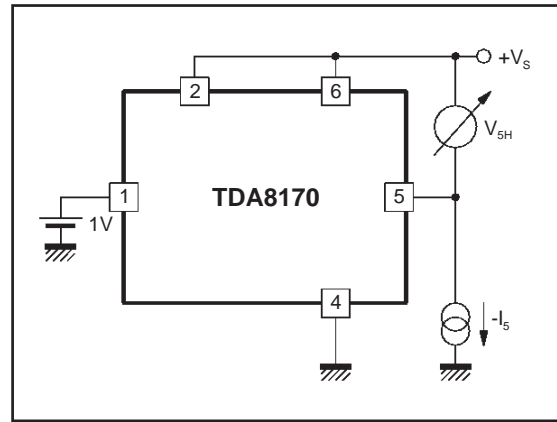
TDA8170

Figure 1a : Measurement of I_1 , I_2 , I_6 , V_7 , $\Delta V_7/\Delta V_S$



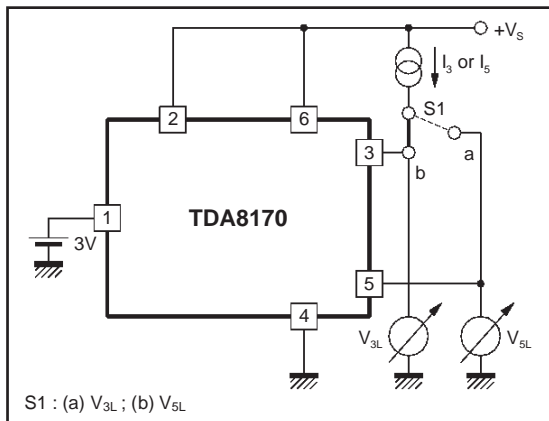
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Figure 1b : Measurement of V_{5H}



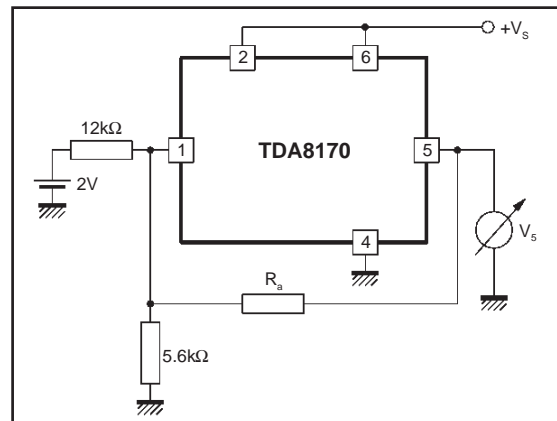
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Figure 1c : Measurement of V_{3L} , V_{5L}



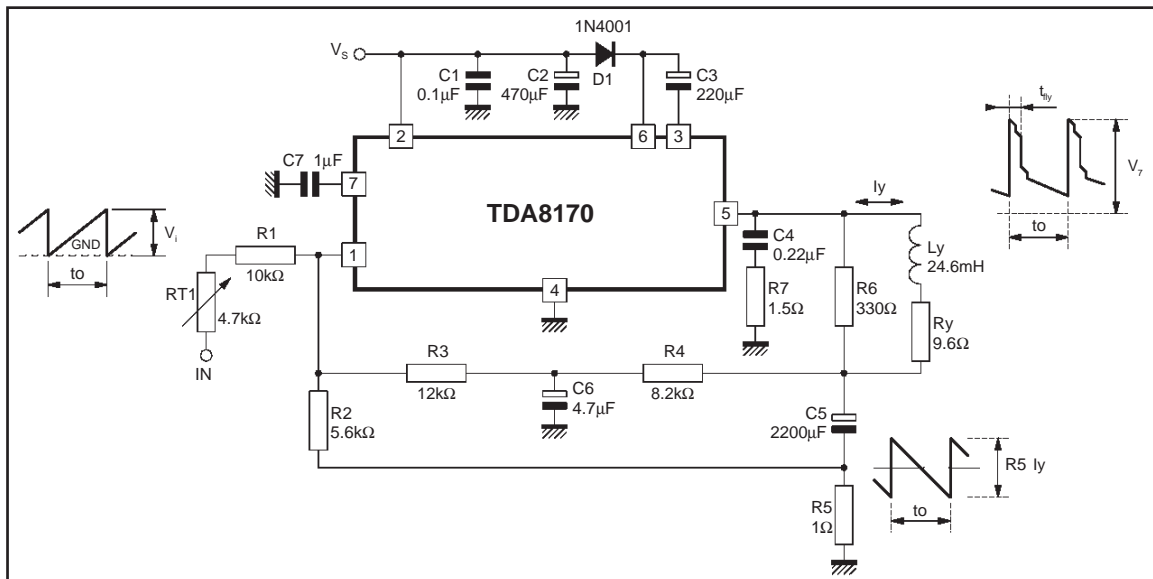
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Figure 1d : Measurement of V_5

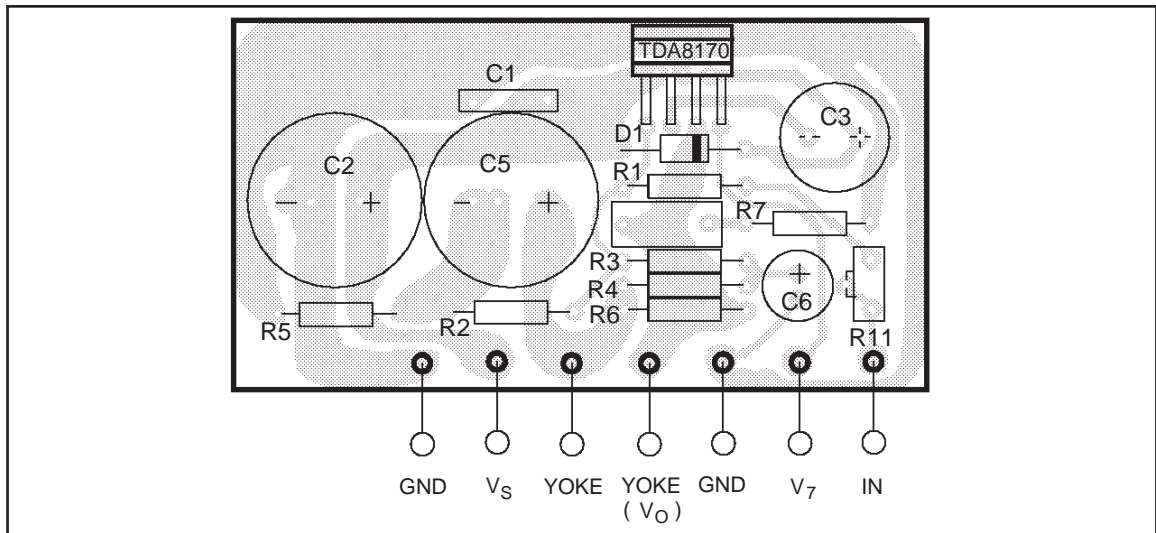


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Figure 2 : Application Schematic



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Figure 3 : PC Board and Component layout of the Circuit of fig. 2(1 : 1 scale)

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COMPONENTS LIST FOR TYPICAL APPLICATIONS

Component	110 ° TVC 5.9 Ω /10 mH 1.95 App	110 ° TVC 9.6 Ω /24.6 mH 1.2 App	90 ° TVC 15 Ω /30 mH 0.82 App	Unit
RT1	10	4.7	10	k Ω
R1	12	10	12	k Ω
R2	10	5.6	5.6	k Ω
R3	27	12	18	k Ω
R4	12	8.2	5.6	k Ω
R5	0.82	1	1	Ω
R6	270	330	330	Ω
R7	1.5	1.5	1.5	Ω
D1	1N 4001	1N 4001	1N 4001	—
C1	0.1	0.1	0.1	μ F
C2 el.	1000/25 V	470/25 V	470/25 V	μ F
C3 el.	220/25 V	220/25 V	220/25 V	μ F
C4	0.22	0.22	0.22	μ F
C5 el.	200/25 V	2200/25 V	1000/16 V	μ F
C6 el.	4.7/16 V	4.7/16 V	10/16 V	μ F
C7	1.0/16V	1.0/16V	1.0/16V	μ F

8170-04.TBL

TYPICAL PERFORMANCES

Parameter	110 ° TVC 5.9 Ω /10 mH	110 ° TVC 9.6 Ω /27 mH	90 ° TVC 15 Ω /30 mH	Unit
V _s - Supply Voltage	24	22.5	25	V
I _s - Current	280	175	125	mA
t _{fly} - Flyback Time	0.6	1	0.7	ms
P _{tot} - Power Dissip.	4.2	2.5	2.05	W
R _{th o-a} - Heatsink	7	13	16	°C/W
T _{amb}	60	60	60	°C
T _{j max}	110	110	110	°C
T _o	20	20	20	ms
V _i	2.5	2.5	2.5	V _{pp}
V ₇	2.5	2.5	2.5	V _p

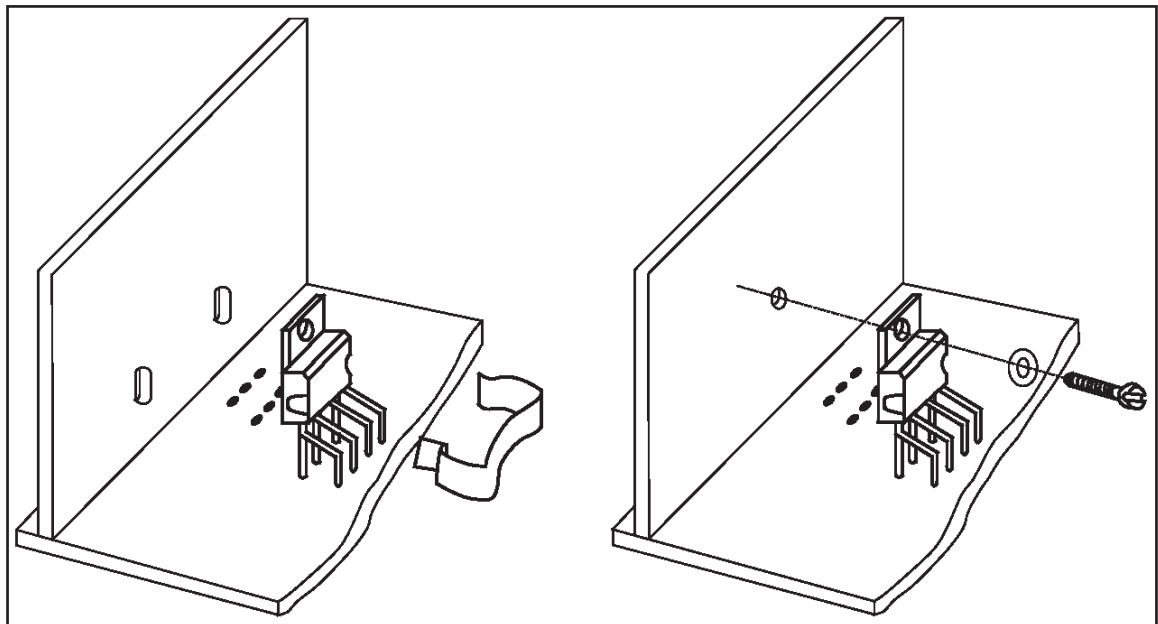
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MOUNTING INSTRUCTIONS

The power dissipated in the circuit must be removed by adding an external heatsink. Thanks to the HEPTAWATT™ package attaching the heatsink is very simple, a screw or a compression

spring (clip) being sufficient. Between the heatsink and the package it is better to insert a layer of silicon grease, to optimize the thermal contact ; no electrical isolation is needed between the two surfaces.

Figure 4 : Mounting Examples



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